

Xinger®



Ultra Low Profile 0805 Balun 50Ω to 50Ω Balanced

Description

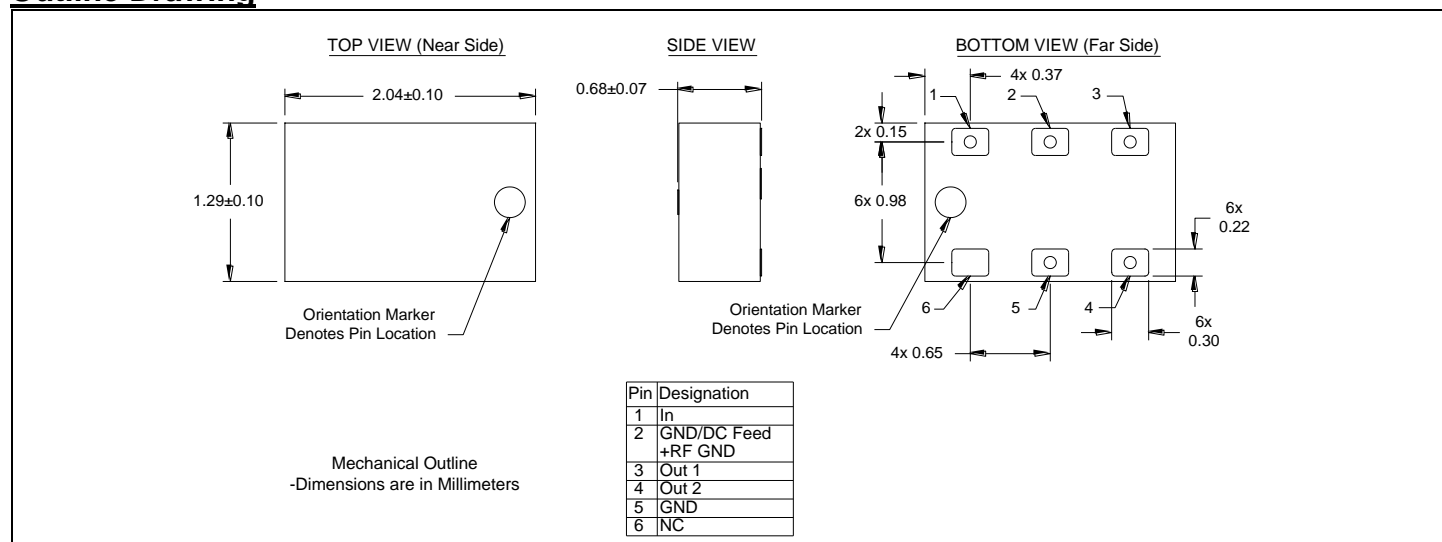
The BD2130J5050AHF is a low profile sub-miniature balanced to unbalanced transformer designed for differential inputs and output locations on next generation wireless chipsets in an easy to use surface mount package covering 802.11b+g+n. The BD2130J5050AHF is ideal for high volume manufacturing and is higher performance than traditional ceramic and lumped element baluns. The BD2130J5050AHF has an unbalanced port impedance of 50Ω and a 50Ω balanced port impedance. This transformation enables single ended signals to be applied to differential ports on modern semiconductors. The output ports have equal amplitude (-3dB) with 180 degree phase differential. The BD2130J5050AHF is available on tape and reel for pick and place high volume manufacturing.

Detailed Electrical Specifications*: Specifications subject to change without notice.

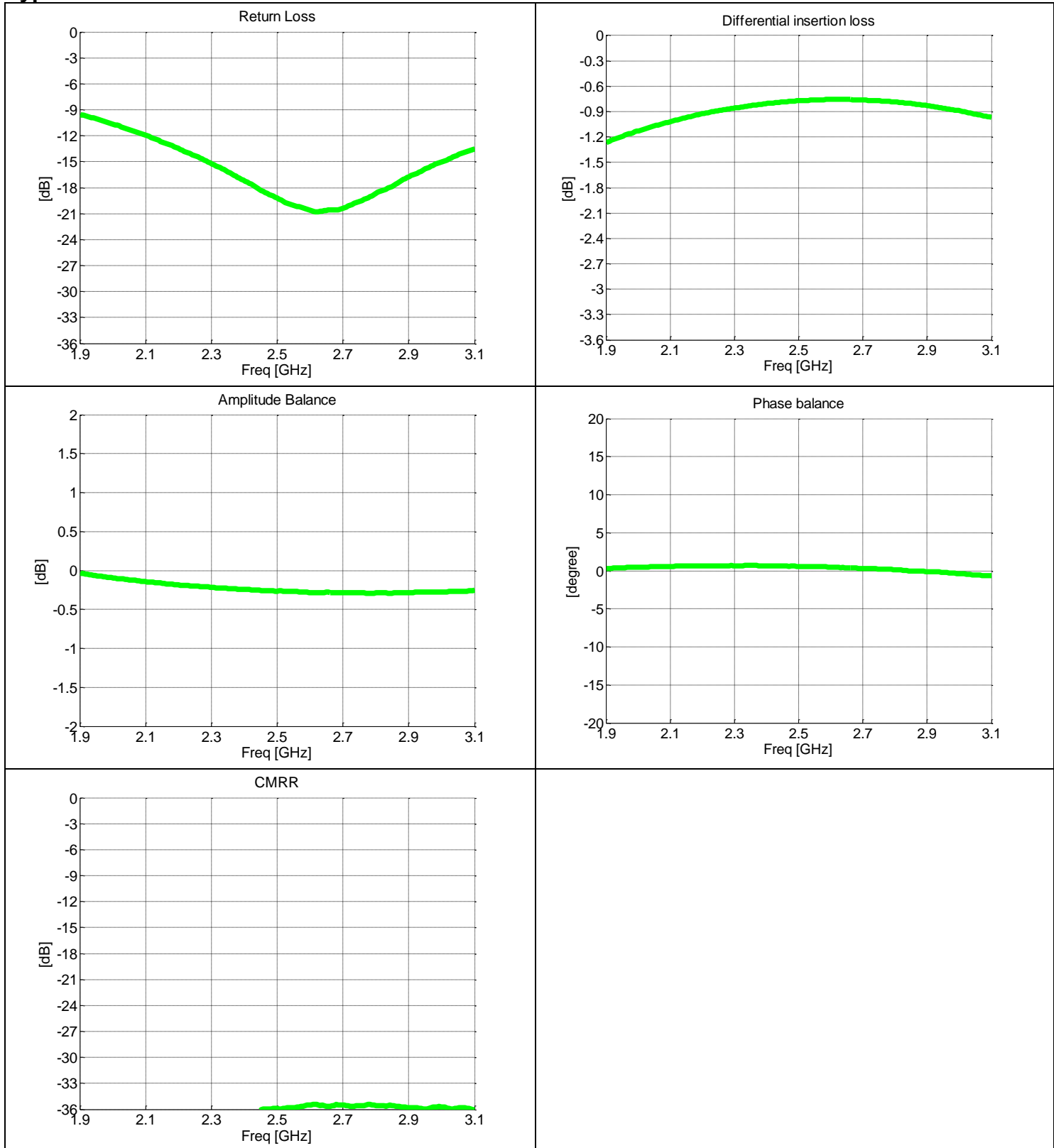
Features:	Parameter	ROOM (25°C)						Unit
		Min.	Typ.	Max	Min.	Typ.	Max	
<ul style="list-style-type: none"> 2.1 – 3.0 GHz 0.7mm Height Profile 50 Ohm to 2 x 25 Ohm 802.11 b & g +n Compliant Low Insertion Loss DCS, PCS & UMTS Input to Output DC Isolation Surface Mountable Tape & Reel Non-conductive Surface RoHS Compliant Halogen Free 	Frequency	2.4		2.5	2.1		3.0	GHz
	Unbalanced Port Imp.		50			50		Ω
	Balanced Port Imp.		50			50		Ω
	Return Loss	12	17		10	12		dB
	Insertion Loss*		0.75	0.9		1.0	1.2	dB
	Amplitude Balance		0.45	0.65		0.7	1.0	dB
	Phase Balance		2	5		2	5	Degrees
	CMRR		35			35		dB
	Power Handling @85C			2			2	Watts
	Power Handling @105C			1.2			1.2	Watts
	Operating Temperature	-55		+105	-55		+105	°C

* Insertion Loss stated at room temperature (Insertion Loss is approximately 0.1 dB higher at +85 °C)

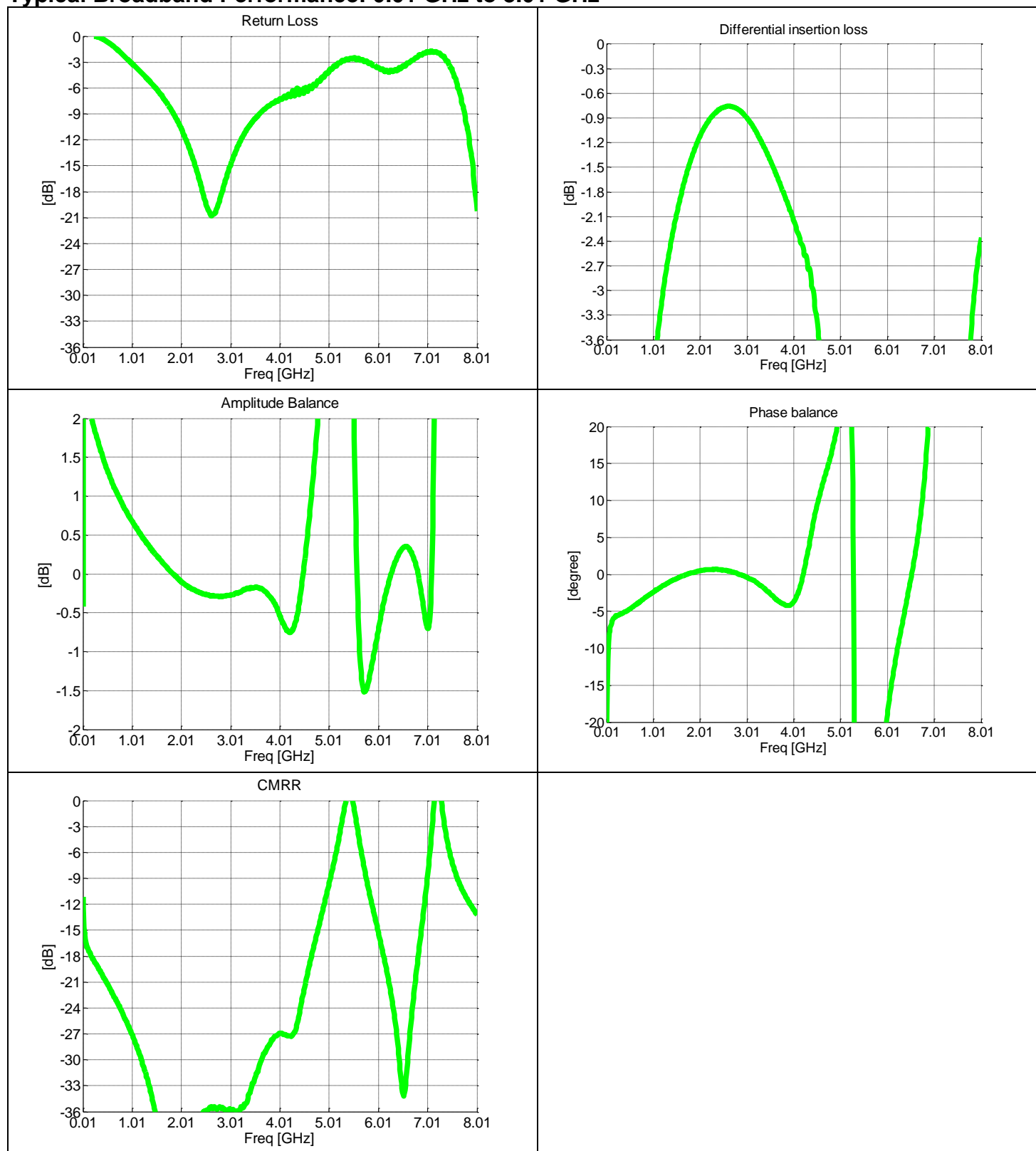
Outline Drawing



Typical Performance: 1.9 GHz. to 3.1 GHz



Typical Broadband Performance: 0.01 GHz to 8.01 GHz



Mounting Configuration:

In order for Xinger surface mount components to work optimally, the proper impedance transmission lines must be used to connect to the RF ports. If this condition is not satisfied, insertion loss, Isolation and VSWR may not meet published specifications.

All of the Xinger components are constructed from organic PTFE based composites which possess excellent electrical and mechanical stability. Xinger components are compliant to a variety of ROHS and Green standards and ready for Pb-free soldering processes. Pads are Gold plated with a Nickel barrier.

An example of the PCB footprint used in the testing of these parts is shown below. An example of a DC-biased footprint is also shown below. In specific designs, the transmission line widths need to be adjusted to the unique dielectric coefficients and thicknesses as well as varying pick and place equipment tolerances.

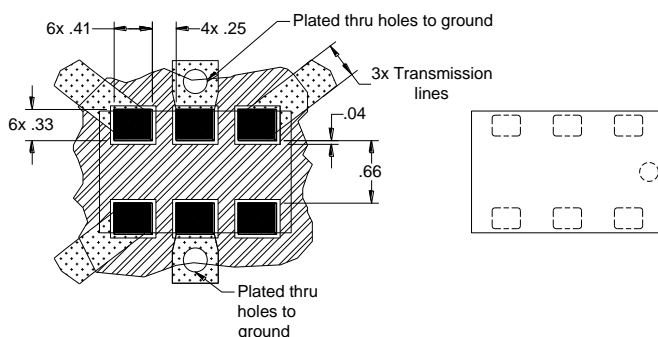
No Bias Footprint

 Circuit Pattern


 Footprint Pad (s)

 Solder Resist

Dimensions are in Millimeters
Mounting Footprint



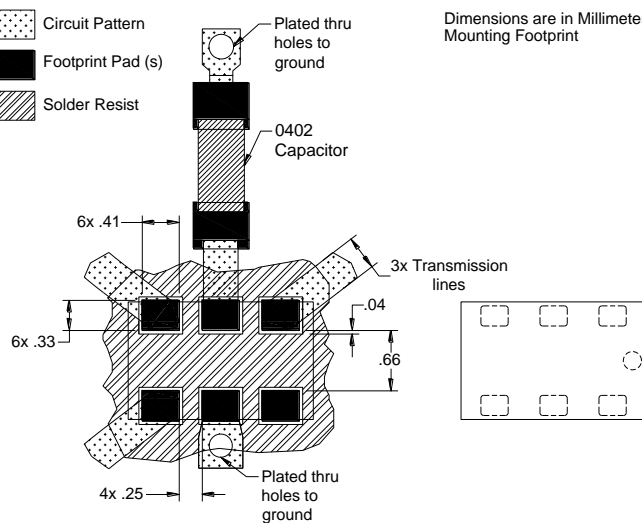
DC Bias Footprint

 Circuit Pattern

 Footprint Pad (s)

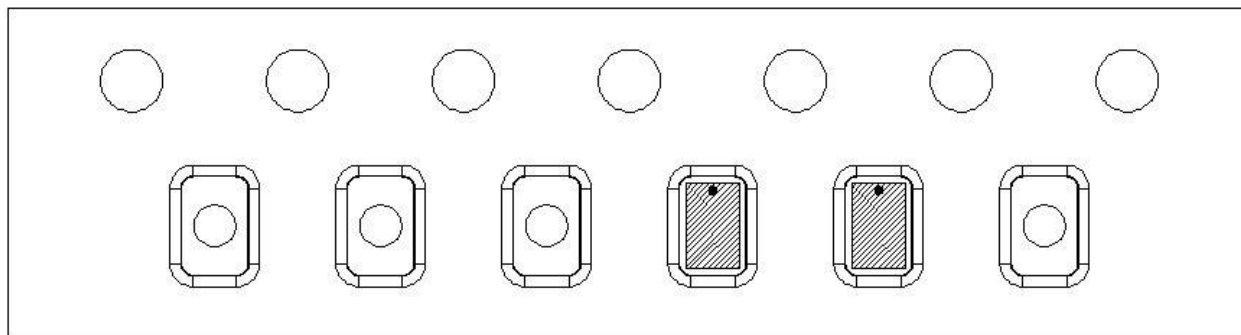
 Solder Resist

Dimensions are in Millimeters
Mounting Footprint



Packaging and Ordering Information

Parts are available in reel and are packaged per EIA 481-D. Parts are oriented in tape and reel as shown below. Minimum order quantities are 4000 per reel.



Direction of
Part Feed
(Unloading)

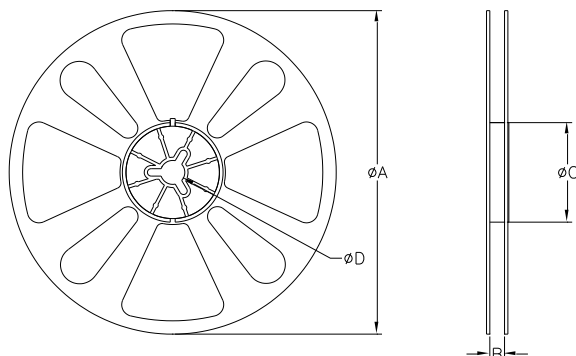


TABLE 1		
QUANTITY/REEL	REEL DIMENSIONS mm	
4000	ϕA	177.80
	B	8.00
	ϕC	50.80
	ϕD	13.00